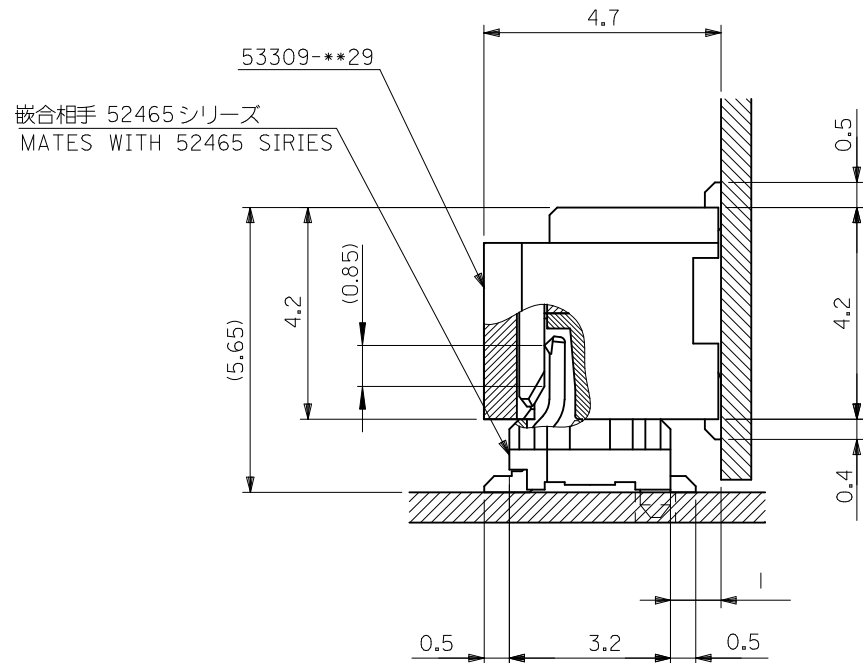


0.4	17.8	16.9	15.2	53309-4029	40	
0.8	17.0	16.1	14.4	-3829	38	
0.4	16.2	15.3	13.6	-3629	36	
0.8	15.4	14.5	12.8	-3429	34	
0.4	14.6	13.7	12.0	-3229	32	
0.8	13.8	12.9	11.2	-3029	30	
0.4	13.0	12.1	10.4	-2829	28	
0.8	12.2	11.3	9.6	-2629	26	
0.4	11.4	10.5	8.8	-2429	24	
0.8	10.6	9.7	8.0	-2229	22	
0.4	9.8	8.9	7.2	-2029	20	
0.8	9.0	8.1	6.4	-1829	18	
0.4	8.2	7.3	5.6	-1629	16	
0.8	7.4	6.5	4.8	-1429	14	
0.4	6.6	5.7	4.0	-1229	12	
53309-**29	0.8	5.8	4.9	3.2	53309-1029	10
MODEL NO.	D	C	B	A	MATERIAL NO.	極数 CKT.

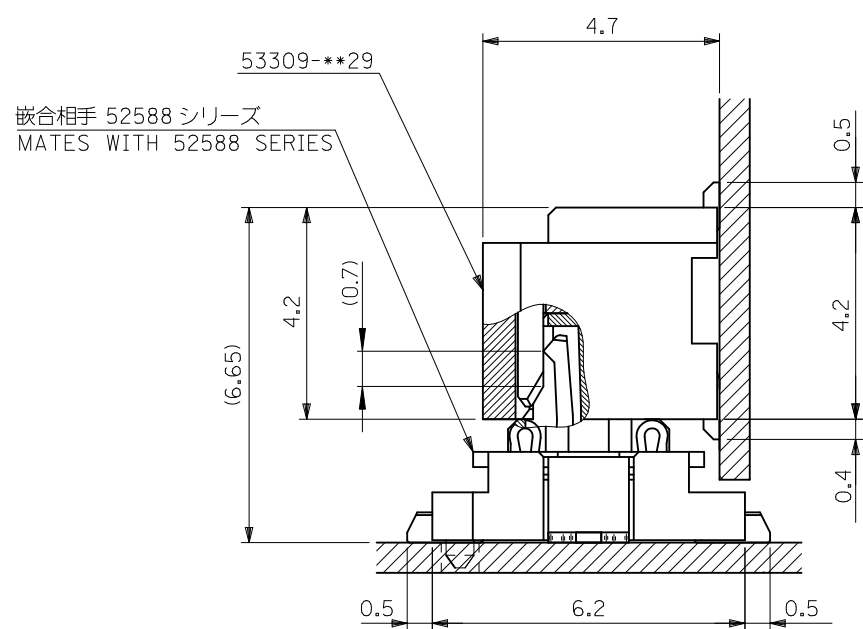
注記 NOTES

1. 嵌合相手: 52465,52588 シリーズ
MATE WITH : 52465,52588 SERIES
2. ウエハーの C から隣接するピンの C 迄の位置を示す。
SHOW POSITION FROM C OF WAFER TO C OF ADJACENT PINS.
3. 本製品は 53309-**27 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53309-**27

REVISED EC NO: J2010-1285 DRWN: YON002 2009/12/17 CHKD: SMARUYAMA 2009/12/17 APPR: SMARUYAMA 2009/12/17	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY M. NINOMIYA	DATE 2004/03/10	TITLE 0.8 B/B CONN.WAFER ASS'Y R/A SMT(WITHOUT BOSS)		
	10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO	DATE 2004/03/10	MOLEX INCORPORATED DOCUMENT NO. SD-53309-011 SHEET NO. 1 OF 2		
	30 OVER	±0.3	APPROVED BY M. SASAO	DATE 2004/03/10			
REV	DESCRIPTION	ANGULAR ±3 °	SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3					



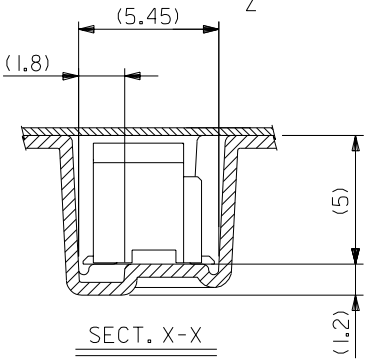
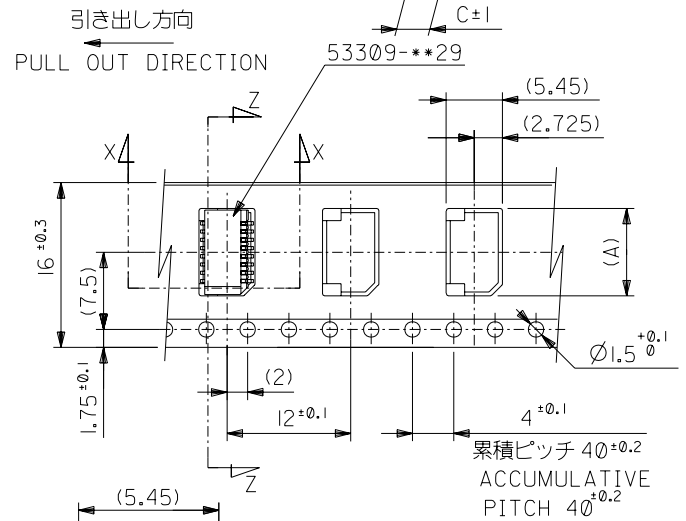
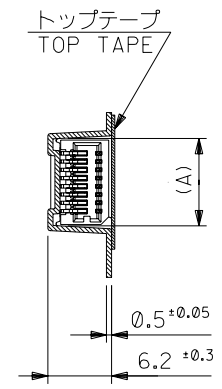
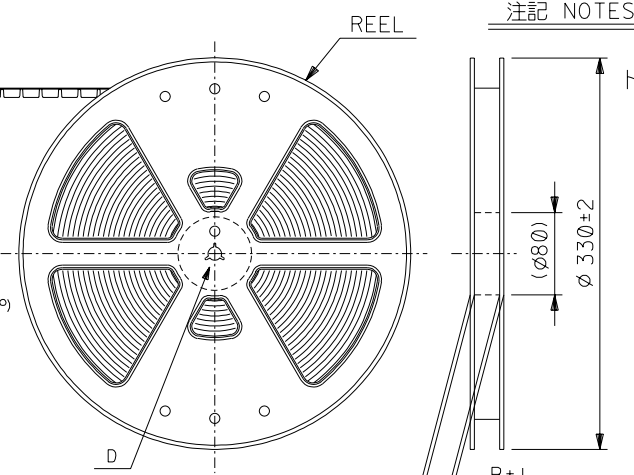
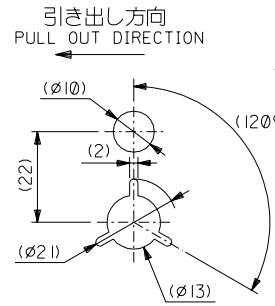
嵌合状態図 (参考)
 MATED DRAWING(REF.)



嵌合状態図 (参考)
 MATED DRAWING(REF.)

REVISED EC NO: J2010-1285 DRWN: YON002 CHKD: SMARUYAMA APPR: SMARUYAMA	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	±0.2	DRAWN BY M. NINOMIYA	DATE 2004/03/10	TITLE 0.8 B/B CONN. WAFER ASS'Y R/A SMT(WITHOUT BOSS)				
		10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO	DATE 2004/03/10	MOLEX INCORPORATED				
		30 OVER	±0.3	APPROVED BY M. SASAO	DATE 2004/03/10	DOCUMENT NO. SD-53309-011				
ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE SHEET 1		SHEET NO. 2 OF 2				
SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								

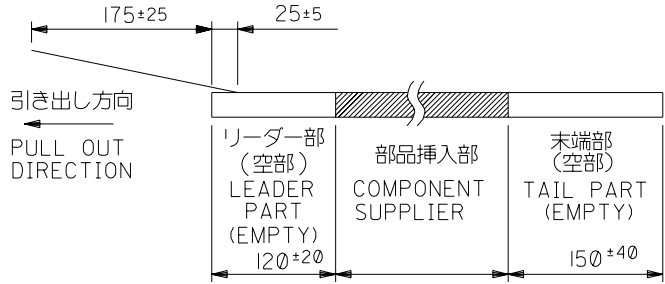
DWG. NO.
SD-53309-012



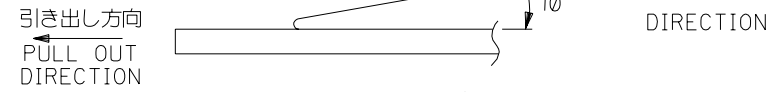
16mm幅キャリアテープ
16mm WIDTH CARRIER TAPE

注記 NOTES

- 梱包数量：1000個/リール NUMBER OF CONNECTORS:1000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH



- トップテープの剥離強度：(剥離方向は下図参照)
0. 1N~1. 3N {10gf~130gf} 尚、本規格値は、出荷時に適用。
(但し、輸送時に剥離が発生しない事。)
PEELING OFF FORCE OF TOP TAPE
0. 1N~1.3N{10gf~130gf} (PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT
PEEL OFF SHOULD NOT BE ALLOWED, DURING TRANSPORTATION



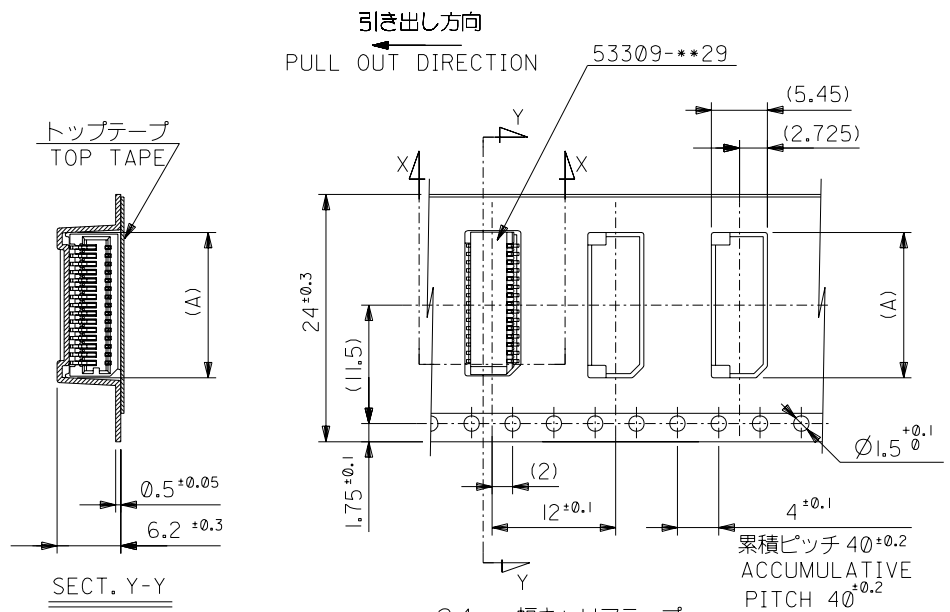
- 材料
キャリアテープ：ポリプロピレン (PP)
トップテープ：PET, PE, PEF
リール：ポリスチレン (PS)
MATERIAL
<リサイクル材を含む>

5. 本製品は 53309-**91 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53309-**91.

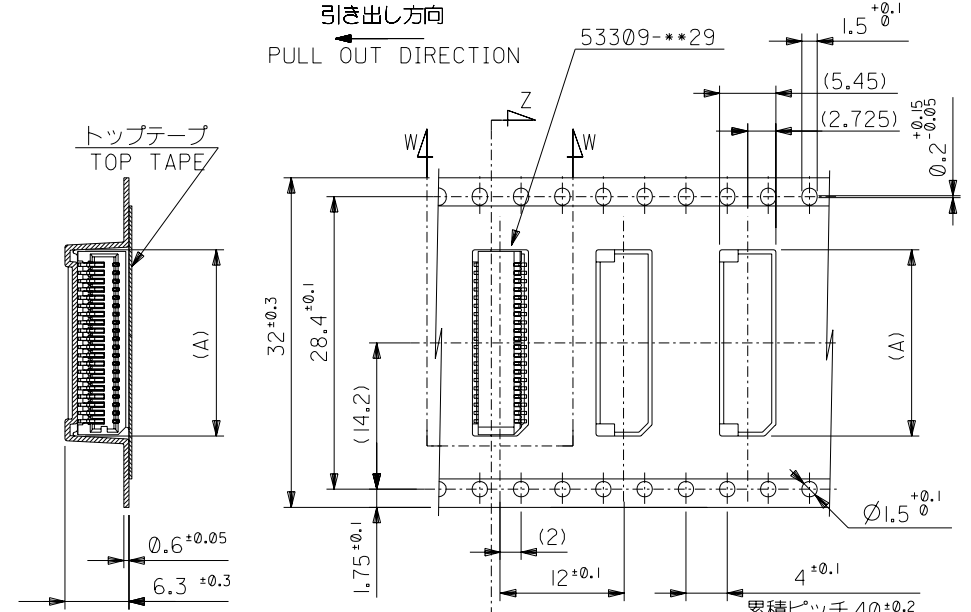
CARRIER TAPE: POLYPROPYLENE
TOP TAPE: PET, PE, PEF
REEL: POLYSTYRENE (PS)
<RECYCLE MATERIAL CONTAINED>

16	21.4	17.4	9.3	53309-1870	18
			8.5	53309-1670	16
			7.7	53309-1470	14
			6.9	53309-1270	12
			6.1	53309-1070	10
キャリアテープ幅 CARRIER TAPE WIDTH	C	B	(A)	MATERIAL NO.	極数 CIRCUIT

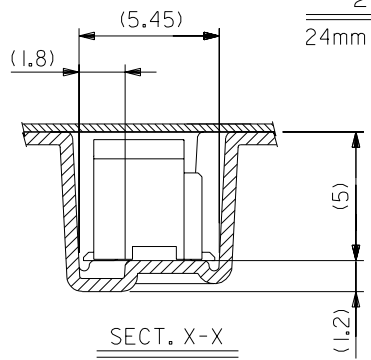
53309-**70		材料 MATERIAL		注記参照 SEE NOTES		molex MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社	
MODEL NO.		仕上げ FINISH		—		REVISE ONLY ON CAD SYSTEM	
角度 ANGLE		+3°		適用電線範囲 WIRE RANGE		TITLE 名称 0.8 BtB Conn Wafer Assy	
30以上 OVER		+0.3		—		RA SMT Without Boss	
10以上 OVER 30未 UNDER		+0.25		被覆外径 INS. RANGE		Embstp Pkg	
未 UNDER		+0.2		—		-LEAD FREE-	
一般公差 GENERAL TOLERANCES		記号 LTR		新規作成 RELEASED (J2004-2995)		DRAWN BY 04/03/10 M.NINOMIYA	
		変更内容 REVISION RECORD		DR. 日付 CHK. DATE		CHK'D BY 04/03/10 K.TOJO	
				APP'D BY 04/03/10 M.SASAO		尺 SCALE	
						DWG. NO. (SHEET 1 OF 2) REV SD-53309-012 0	



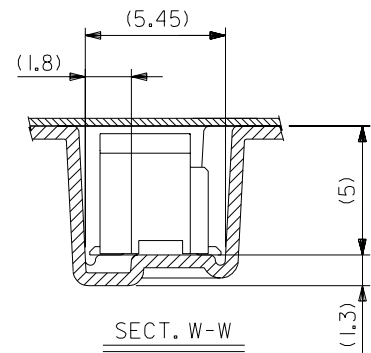
24mm幅キャリアテープ
24mm WIDTH CARRIER TAPE



32mm幅キャリアテープ
32mm WIDTH CARRIER TAPE



SECT. X-X



SECT. W-W

24	29.4	25.4	16.5	53309-3670	36
			15.7	53309-3470	34
			14.9	53309-3270	32
			14.1	53309-3070	30
			13.3	53309-2870	28
			12.5	53309-2670	26
			11.7	53309-2470	24
			10.9	53309-2270	22
10.1	53309-2070	20			
キャリアテープ幅 CARRIER TAPE WIDTH	C	B	(A)	MATERIAL NO.	極数 CIRCUIT

53309-***70		M.N.		04/03/10	
MODEL NO.		DR.	日付	CHK.	DATE
角度 ANGLE	+3°	DR. CHK.	日付	CHK.	DATE
30以上 OVER	+0.3	DR. CHK.	日付	CHK.	DATE
10以上 OVER	+0.25	DR. CHK.	日付	CHK.	DATE
30未満 UNDER	+0.2	DR. CHK.	日付	CHK.	DATE
10未満 UNDER	+0.2	DR. CHK.	日付	CHK.	DATE
一般公差 GENERAL TOLERANCES		記号 LTR	変更内容 REVISION RECORD	新規作成 RELEASED (J2004-2995)	M.N. 04/03/10

32	37.4	33.4	18.1	53309-4070	40
キャリアテープ幅 CARRIER TAPE WIDTH	C	B	(A)	MATERIAL NO.	極数 CIRCUIT
			17.3	53309-3870	38

材料 MATERIAL
SHEET 1 OF 2 参照 REFER TO SHEET 1 OF 2
仕上げ FINISH —
適用電線範囲 WIRE RANGE —
被覆外径 INS. RANGE —
DRAWN BY 04/03/10 M.NINOMIYA
CHK'D BY 04/03/10 K.TOJO
APP'D BY 04/03/10 M.SASAO
MATERIAL NO. 53309-4070
REVISE ONLY ON CAD SYSTEM
TITLE 名称 0.8 BtB Wafer Assy
RA SMT Without Boss
Embstp Pkg
-LEAD FREE-
DWG. NO. (SHEET 2 OF 2) REV 0
SD-53309-012